# S2S5 Series

# V<sub>DRM</sub>: 600V, Cost effective Non-zero cross type **Mini-Flat Package** Phototriac Coupler for triggering



# Description

S2S5 Series Phototriac Coupler include an infrared emitting diode (IRED) optically coupled to an output Phototriac.

These devices feature full wave control and are ideal isolated drivers for medium to high current Triacs.

SOP package provides 3.75kV isolation from input to output with superior commutative noise immunity.

### Features

- 1. High repetitive peak off-state voltage (V<sub>DRM</sub> : 600V)
- 2. Non-zero crossing functionality
- 3. IFT ranks available (see Model Line-up section in this datasheet)
- 4. 4pin Mini-flat package
- 5. Superior noise immunity (dV/dt : MIN. 500V/µs)
- 6. Double transfer mold construction (Ideal for Flow Soldering)
- 7. High isolation voltage between input and output (Viso(rms) : 3.75kV)

# Agency approvals/Compliance

- 1. Recognized by UL1577 (Double protection isolation), file No. E64380 (as model No. S2S5)
- 2. Approved by CSA, file No. CA95323 (as model No. S2S5)
- 3. Optionary available VDE Approved (\*)(DIN EN 60747-5-2), file No. 40009162 (as model No. S2S5)
- 4. Package resin : UL flammability grade (94V-0)

(\*) DIN EN60747-5-2 : successor standard of DIN VDE0884. Up to Date code "RD" (December 2003), approval of DIN VDE0884. From Date code "S1" (January 2004), approval of DIN EN60747-5-2.

# Applications

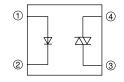
- 1. Triggering for Triacs used to switch on and off devices which require AC Loads. For example heaters, fans, motors, solenoids, and valves.
- 2. Triggering for Triacs used for implementing phase control in applications such as lighting control and temperature control (HVAC).
- 3. AC line control in power supply applications.

Notice The content of data sheet is subject to change without prior notice

In the absence of confirmation by device specification sheets, SHARP takes no responsibility for any defects that may occur in equipment using any SHARP devices shown in catalogs, data books, etc. Contact SHARP in order to obtain the latest device specification sheets before using any SHARP device.



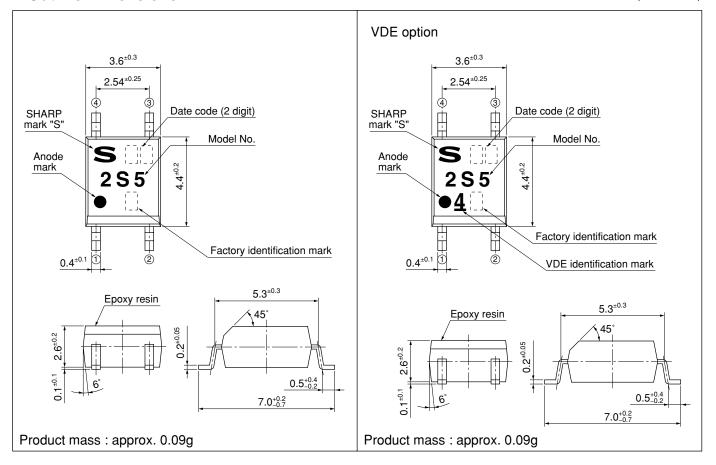
#### Internal Connection Diagram



① Anode

- 2 Cathode
- ③ Anode/Cathode④ Cathode/Anode
- Outline Dimensions

(Unit : mm)





# Date code (2 digit)

	1st o	digit		2nd digit		
	Year of p	roduction		Month of production		
A.D.	Mark	A.D	Mark	Month	Mark	
1990	A	2002	Р	January	1	
1991	В	2003	R	February	2	
1992	C	2004	S	March	3	
1993	D	2005	Т	April	4	
1994	Е	2006	U	May	5	
1995	F	2007	V	June	6	
1996	Н	2008	W	July	7	
1997	J	2009	Х	August	8	
1998	K	2010	А	September	9	
1999	L	2011	В	October	0	
2000	М	2012	С	November	N	
2001	N	:	:	December	D	
2001	N	:	:	December	D	

repeats in a 20 year cycle

# Factory identification mark

Factory identification Mark	Country of origin	
no mark	I	
	Japan	
	Indonesia	
$\overline{}$	Philippines	
	China	

\* This factory marking is for identification purpose only.

Please contact the local SHARP sales representative to see the actural status of the production.

# Rank mark

There is no rank mark indicator.

0.2mm or more

Soldering area

# ■ Absolute Maximum Ratings

■ Absolute Maximum Ratings (T <sub>a</sub> =25°C)					
	Parameter	Symbol	Rating	Unit	
T	Forward current	I <sub>F</sub>	50	mA	
Input	Reverse voltage	V <sub>R</sub>	6	V	
RMS ON-state current		I <sub>T</sub> (rms)	0.05	А	
Output	Peak one cycle surge current	I <sub>surge</sub>	0.6 *3	А	
	Repetitive peak OFF-state voltage	V <sub>DRM</sub>	600	V	
<sup>*1</sup> Isolation voltage		V <sub>iso</sub> (rms)	3.75	kV	
Operating temperature		T <sub>opr</sub>	-30 to +100	°C	
Storage temperature		T <sub>stg</sub>	-40 to +125	°C	
* <sup>2</sup> Soldering temperature		T <sub>sol</sub>	260	°C	

\*1 40 to 60%RH, AC for 1minute, f=60Hz \*2 For 10s

\*3 f=50Hz sine wave

# ■ Electro-optical Characteristics

(1a-23								a =0 0)
Parameter			Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Tt	Forward voltage		V <sub>F</sub>	I <sub>F</sub> =20mA	-	1.2	1.4	V
Input	Reverse current	Reverse current		V <sub>R</sub> =3V		-	10	μΑ
	Repentitive peak OFF-state	current	I <sub>DRM</sub>	$V_D = V_{DRM}$	-	-	1	μΑ
Output	ON-state voltage		VT	I <sub>T</sub> =0.05A	-	-	2.5	V
	Holding current		I <sub>H</sub>	V <sub>D</sub> =6V	0.1	-	3.5	mA
	Critical rate of rise of OFF-state voltage		dV/dt	$V_D=1/\sqrt{2} \cdot V_{DRM}$	500	-	-	V/µs
Transfer Minimum trigger current charac- teristics Isolation resistance	No rank	т	V (V D 1000	-	-	10		
	Minimum trigger current	Rank R	I <sub>FT</sub>	$V_D=6V, R_L=100\Omega$	_	-	7	mA
	Isolation resistance		R <sub>ISO</sub>	DC500V, 40 to 60%RH	5×10 <sup>10</sup>	1011	-	Ω
	Turn-on time		t <sub>on</sub>	$V_D=6V, R_L=100\Omega, I_F=20mA$	-	-	100	μs

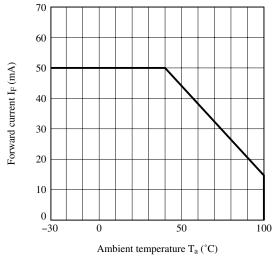
### ■ Model Line-up

Shipping Packag	Sleeve		Taping			I <sub>FT</sub> [mA]	
	e 100pcs/sleeve		3 000pcs/reel		<b>.</b> .		
DIN EN60747-5-2		Approved		Approved	I <sub>F⊺</sub> rank	$(V_D = 6V, R_1 = 100\Omega)$	
Madal Na	S2S5000F	S2S5Y00F	S2S5A00F	S2S5AY0F	No rank	MAX. 10	
Model No.	S2S5R00F	S2S5RY0F	S2S5RA0F	S2S5RAYF	Rank R	MAX. 7	

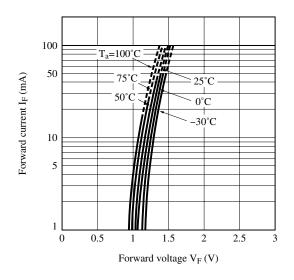
Please contact a local SHARP sales representative to inquire about production status.



# Fig.1 Forward Current vs. Ambient Temperature



# Fig.3 Forward Current vs. Forward Voltage





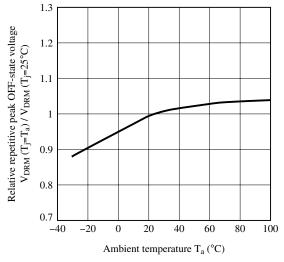
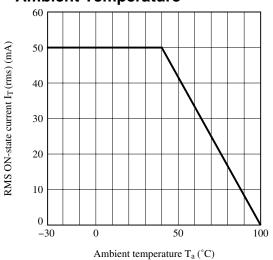
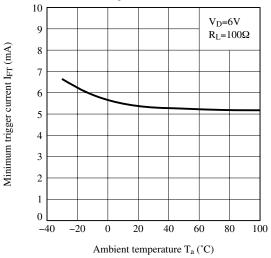


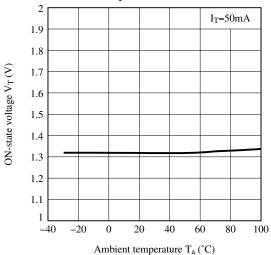
Fig.2 RMS ON-state Current vs. Ambient Temperature



# Fig.4 Minimum Trigger Current vs. Ambient Temperature



# Fig.6 ON-state Voltage vs. Ambient Temperature





# Fig.7 Holding Current vs. Ambient Temperature

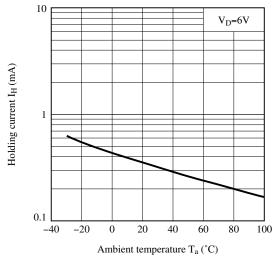
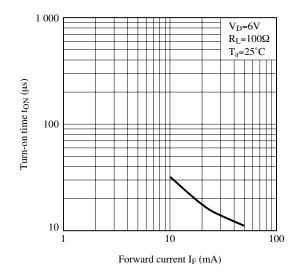
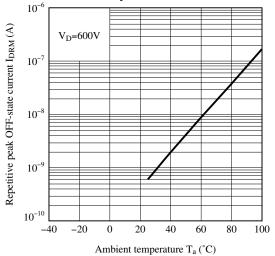


Fig.9 Turn-on Time vs. Forward Current



Remarks : Please be aware that all data in the graph are just for reference.

# Fig.8 Repetitive Peak OFF-state Current vs. Ambient Temperature





#### Design Considerations

#### Design guide

In order for the Phototriac to turn off, the triggering current  $(I_F)$  must be 0.1mA or less.

Please refrain from using these devices in a direct drive configuration.

These Phototriac Coupler are intended to be used as triggering device for main Triacs.

Please ensure that the output rating of these devices will be sufficient for triggering the main output Triac of your choice. Failure to do may result in malfunctions.

In phase control applications or where the Phototriac Coupler is being by a pulse signal, please ensure that the pulse width is a minimum of 1ms.

For designs that will experience excessive noise or sudden changes in load voltage, please include an appropriate snubber circuit as shown in the below circuit.

Please keep in mind that Sharp Phototriac Couplers incorporate superor dV/dt ratings which can often eliminate the need for a snubber circuit.

#### Degradation

In general, the emission of the IRED used in Phototriac Couplers will degrade over time.

In the case where long term operation and / or constant extreme temperature fluctuations will be applied to the devices, please allow for a worst case scenario of 50% degradation over 5years.

Therefore in order to maintain proper operation, a design implementing these Phototriac Couplers should provide at least twice the minimum required triggering current from initial operation.

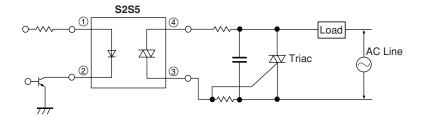
# 

# • Recommended Foot Print (reference)

(Unit : mm)



### • Standard Circuit (Medium/High Power Triac Drive Circuit)



Note) Please add the snubber circuit according to a condition. Any snubber or varistor used for the above mentioned scenarios should be located as close to the main output triac as possible.

☆ For additional design assistance, please review our corresponding Optoelectronic Application Notes.

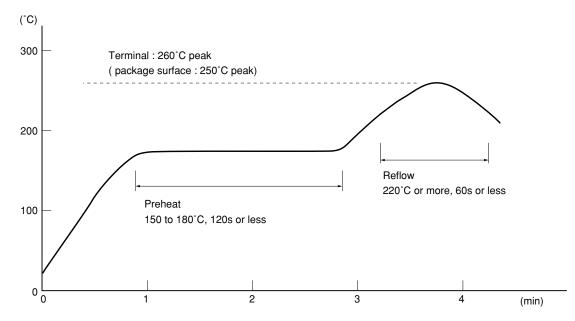


#### Manufacturing Guidelines

#### Soldering Method

**Reflow Soldering:** 

Reflow soldering should follow the temperature profile shown below. Soldering should not exceed the curve of temperature profile and time. Please don't solder more than twice.



#### Flow Soldering :

Due to SHARP's double transfer mold construction submersion in flow solder bath is allowed under the below listed guidelines.

Flow soldering should be completed below 260°C and within 10s. Preheating is within the bounds of 100 to 150°C and 30 to 80s. Please don't solder more than twice.

#### Hand soldering

Hand soldering should be completed within 3s when the point of solder iron is below 400°C. Please don't solder more than twice.

#### Other notices

Please test the soldering method in actual condition and make sure the soldering works fine, since the impact on the junction between the device and PCB varies depending on the tooling and soldering conditions.



#### • Cleaning instructions

Solvent cleaning :

Solvent temperature should be 45°C or below. Immersion time should be 3minutes or less.

#### Ultrasonic cleaning :

The impact on the device varies depending on the size of the cleaning bath, ultrasonic output, cleaning time, size of PCB and mounting method of the device.

Therefore, please make sure the device withstands the ultrasonic cleaning in actual conditions in advance of mass production.

#### Recommended solvent materials :

Ethyl alcohol, Methyl alcohol and Isopropyl alcohol.

In case the other type of solvent materials are intended to be used, please make sure they work fine in actual using conditions since some materials may erode the packaging resin.

#### Presence of ODC

This product shall not contain the following materials.

And they are not used in the production process for this device.

Regulation substances : CFCs, Halon, Carbon tetrachloride, 1.1.1-Trichloroethane (Methylchloroform) Specific brominated flame retardants such as the PBBOs and PBBs are not used in this product at all.



#### ■ Package specification

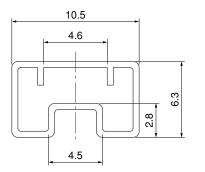
#### Sleeve package

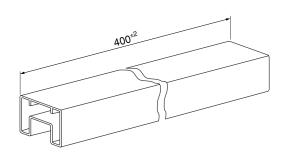
Package materials Sleeve : HIPS (with anti-static material) Stopper : Styrene-Elastomer

#### Package method

MAX. 100pcs of products shall be packaged in a sleeve.Both ends shall be closed by tabbed and tabless stoppers.The product shall be arranged in the sleeve with its anode mark on the tabless stopper side.MAX. 50 sleeves in one case.

#### Sleeve outline dimensions





(Unit : mm)



#### • Tape and Reel package

# 3 000pcs/reel

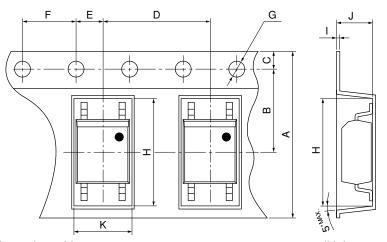
Package materials

Carrier tape : A-PET (with anti-static material)

Cover tape : PET (three layer system)

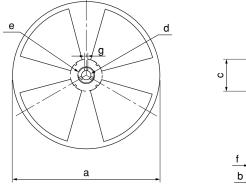
Reel : PS

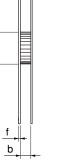
Carrier tape structure and Dimensions



Dimensions List (Unit : mr							
А	В	С	D	E	F	G	
12.0 <sup>±0.3</sup>	$5.5^{\pm 0.1}$	$1.75^{\pm 0.1}$	$8.0^{\pm0.1}$	$2.0^{\pm 0.1}$	$4.0^{\pm 0.1}$	φ1.5+8.1	
Н	Ι	J	K				
$7.4^{\pm 0.1}$	$0.3^{\pm 0.05}$	$3.1^{\pm 0.1}$	$4.0^{\pm 0.1}$				

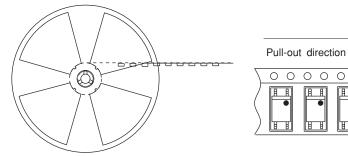
#### Reel structure and Dimensions





[	Dimensio	ns List	(Unit : mm)		
	а	b	с	d	
	370	$13.5^{\pm 1.5}$	80 <sup>±1.0</sup>	13 <sup>±0.5</sup>	
	e	f	g		
	21 <sup>±1.0</sup>	$2.0^{\pm 0.5}$	$2.0^{\pm 0.5}$		

# Direction of product insertion



[Packing	: 3 000pcs/reel]	

00 0

A A A